



Features

- 8 Pin Flatpack or DIP Package (PCMCIA Compatible)
- · Couples Analog and Digital Signals

An ${f IXYS}$ Company

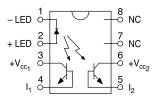
- Wide Bandwidth (>200kHz)
- · High Gain Stability
- Low Input/Output Capacitance
- Low Power Consumption
- 0.01% Servo Linearity
- THD 87dB Typical
- Machine Insertable, Wave Solderable
- · Surface Mount and Tape Reel Versions Available
- VDE Compatible

Applications

- Modem Transformer Replacement With No Insertion Loss
- Digital Telephone Isolation
- Power Supply Feedback Voltage/Current
- · Medical Sensor Isolation
- · Audio Signal Interfacing
- Isolation of Process Control Transducers

Pin Configuration

LOC112 Pinout



Description

The LOC112 Single Linear Optocoupler features an infrared LED optically coupled with two phototransistors. One feedback (input) phototransistor is used to generate a control signal that provides a servomechanism to the LED drive current, thus compensating for the LEDs nonlinear time and temperature characteristics. The other (output) phototransistor provides an output signal that is linear with respect to the servo LED current. The product features wide bandwidth, high input to output isolation and excellent servo linearity.

Approvals

- UL Recognized: File Number E76270
- CSA Certified: File Number LR 43639-10
- BSI Certified:
 - BS EN 60950:1992 (BS7002:1992) Certificate #:7344
 - BS EN 41003:1993 Certificate #:7344

Ordering Information

Part #	Description
L0C112	8 Pin DIP (50/Tube)
LOC112P	8 Pin Flatpack (50/Tube)
LOC112PTR	8 Pin Flatpack (1000/Reel)
LOC112S	8 Pin Surface Mount (50/Tube)
LOC112STR	8 Pin Surface Mount (1000/Reel)

K3 Sorted Bins

Bin D	=	0.733-0.805
Bin E	=	0.806-0.886
Bin F	=	0.887-0.974
Bin G	=	0.733-1.072

- The LOC112 is shipped in anti-static tubes of 50 pieces. Each tube will contain one K3 sorted bin.
- Bin designation marked on each device (D G).



Rev. 4.0

Absolute Maximum Ratings (@ 25° C)

Parameter	Min	Тур	Max	Units
Input Power Dissipation	-	-	150 ¹	mW
Input Control Current	-	-	100	mA
Peak (10ms)	-	-	1	Α
Total Package Dissipation	-	-	500 ²	mW
Isolation Voltage Input to Output				
SOIC Package	3750	-	-	V _{RMS}
Operational Temperature	-40		+85	°C
Storage Temperature	-40	-	+125	٦°
Soldering Temperature (10 Seconds Max)	-	-	+260	°C
Flatpack Package	-	-	+220	°C

Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.

¹ Derate Linearly 1.33 mW/°C

² Derate Linearly 6.67 mW/°C

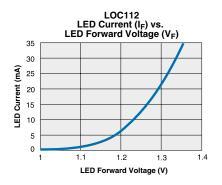
Electrical Characteristics

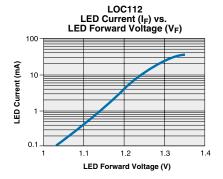
Parameter	Conditions	Symbol	Min	Тур	Max	Units
Input Characteristics @ 25°C						-
LED Voltage Drop	I _F =2-10mA	V _F	0.9	1.2	1.4	V
Reverse LED Current	V _R =5V	I _R	-	-	10	μA
Reverse LED Voltage	-	V _R	-	-	5	V
Forward LED Current	-	I _F	-	-	100	mA
Coupler/Detector Characteristic	cs @ 25°C	1				
Dark Current	I _F =0mA, V _{CC} =15V	I I _D	-	1	25	nA
K1, Servo Gain (I ₁ /I _F)	I _F =2-10mA, V _{CC} =15V	K1	0.004	0.007	0.030	-
K2, Forward Gain (I ₂ /I _F)	I _F =2-10mA, V _{CC} =15V	K2	0.004	0.007	0.030	-
K3, Transfer Gain $(K_2/K_1)^1$	I _F =2-10mA, V _{CC} =15V	K3	0.733	1.0	1.072	-
Δ K3, Transfer Gain Linearity ¹	I _F =2-10mA	ΔK3	-	-	1.0	%
(non-servoed)						
K3 Temperature Coefficient	I _F =2-10mA, V _{det} =-5V	Δ K3/ Δ T	-	0.005	-	%/°C
Common Mode	V=20V _{P-P} , R _L =2KΩ,	CMRR	-	130	-	dB
Rejection Ratio	F=100Hz					
Total Harmonic Distortion	F ₀ =350Hz, 0dBm	THD	-96	-87	-80	dB
Frequency Response	Photoconductive Operation	BW (-3dB)	-	200	-	kHz
	Photovoltaic Operation	BW (-3dB)	-	40	-	kHz
Input/Output Capacitance	-	C _{I/O}	-	3	-	pF
Input/Output Isolation	-	V _{I/O}	3750	-	-	V _{RMS}

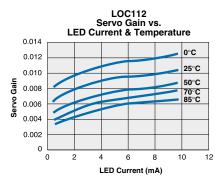
¹ LOC111 and LOC112 Bins D,E,F,G.

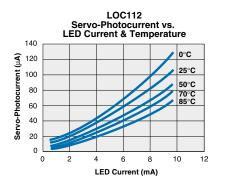


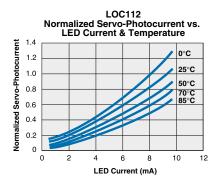
PERFORMANCE DATA*

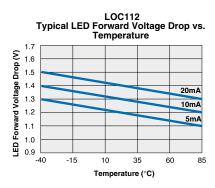












* The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.

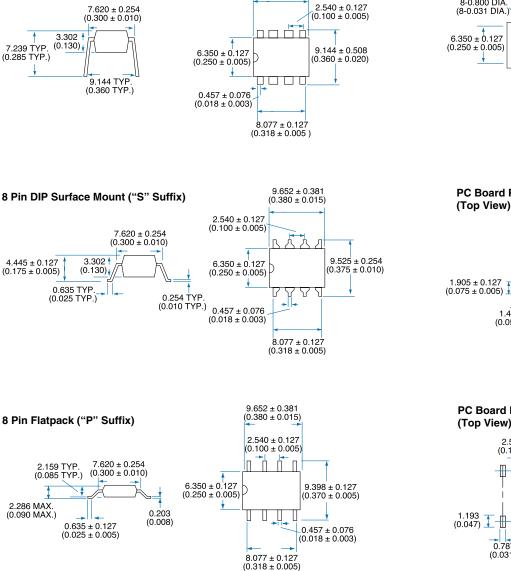
Downloaded from Elcodis.com electronic components distributor

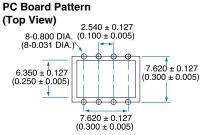
8 Pin DIP Through Hole (Standard)

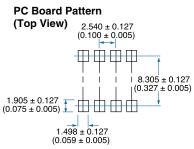


MECHANICAL DIMENSIONS

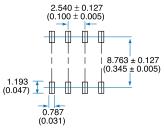
9.652 ± 0.381 (0.380 ± 0.015)







PC Board Pattern (Top View)

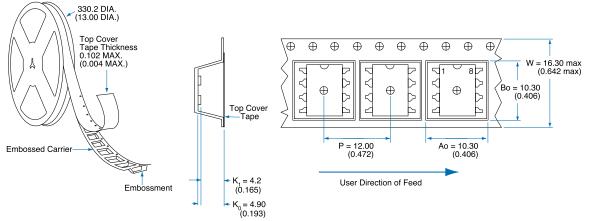


Dimensions mm (inches)



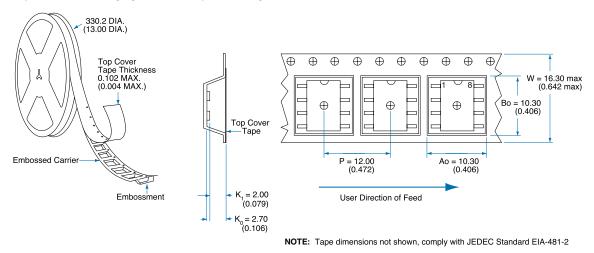
MECHANICAL DIMENSIONS

Tape and Reel Packaging for 8 Pin Surface Mount Package



NOTE: Tape dimensions not shown, comply with JEDEC Standard EIA-481-2

Tape and Reel Packaging for 8 Pin Flatpack Package



<u>Dimensions</u> mm (inches)

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